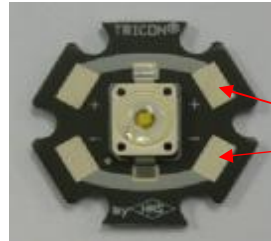


Manual Soldering Process (Recommended)



This application note intends to provide guidelines for manual soldering technique for TRICON® board. Too high temperature or prolong time of exposure to high heat may damage the solder pads.

Make sure the wires solder pad is free from the solder paste during reflow.



NO NEED to apply solder paste at the wires solder pad.

Soldering condition as below:

Soldering Tip Temperature: 360~400°C Max (Depend on the board size)

Soldering Time: 3 sec. Max (one time only).

Wire pre-tinned: either by dipping into solder pot or soldering iron. **(MUST)**

It is recommended to use the below option for your soldering especially for the big board size. For small board, it may use the normal soldering iron power for the soldering, but need to re-confirm by your internal processes.

Option 1: By using the Hot plate.



Hot plate

Recommended hot plate temperature: 80~100 °C (Depend on the board size)

Option 2: By using more power solder iron - recommended 60Watt

Note:

Repairing should not be done after the lead wires have been soldered. When repairing is unavoidable, a hot plate should be used. After soldering, do not allow to pull the lead wires while the board is still in hot condition.

23-May-09 Revision 03